12V P-CHANNEL ENHANCEMENT MODE MOSFET

NEW PRODUCT

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)\ max}$	$I_{D\ MAX}$ T_A = +25°C
-12V	0.8 Ω @ V_{GS} = -4.5V	-0.2A
	1.1 Ω @ V_{GS} = -2.5V	
	3.0 Ω @ V_{GS} = -1.8V	
	5.0 Ω @ V_{GS} = -1.5V	

Description

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- Power Management Functions
- Portable Power Adaptors

Features

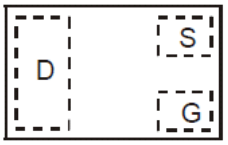
- 0.4mm Ultra Low Profile Package for Thin Application
- 0.48mm^2 Package Footprint, 16 Times Smaller than SOT23
- Low On-Resistance
- Low Input Capacitance
- ESD Protected Gate
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

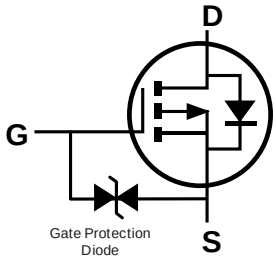
- Case: X2-DFN0806-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.00043 grams (Approximate)

X2-DFN0806-3

Bottom View



Top View
Package Pin Configuration



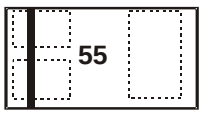
Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1555UFA-7B	X2-DFN0806-3	10,000/Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Top View
Bar Denotes Gate and Source Side

55 = Product Type Marking Code

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	-12	V
Gate-Source Voltage		V_{GSS}	±8	
Continuous Drain Current (V_{GS} = -4.5V)	(Note 5)	I_D	-0.2	A
Pulsed Drain Current	(Note 6)	I_{DM}	-1.5	A

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation	(Note 5)	P_D	0.36	W
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	353	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	-1	µA	V_{DS} = -10V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±10	µA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.4	—	-1.0	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	—	0.4	0.8	Ω	V_{GS} = -4.5V, I_D = -0.2A
		—	0.55	1.1		V_{GS} = -2.5V, I_D = -0.1A
		—	0.75	3.0		V_{GS} = -1.8V, I_D = -0.05A
		—	1.0	5.0		V_{GS} = -1.5V, I_D = -0.01A
Diode Forward Voltage	V_{SD}	—	—	-1.2	V	V_{GS} = 0V, I_S = -0.2A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	55.4	—	pF	V_{DS} = -10V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	14.7	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	11.9	—	pF	
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	0.84	—	nC	V_{DS} = -6V, V_{GS} = -4.5V, I_D = -0.2A
Gate-Source Charge	Q_{gs}	—	0.12	—	nC	
Gate-Drain Charge	Q_{gd}	—	0.23	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	16	—	ns	V_{DD} = -6V, V_{GS} = -4.5V, I_D = -0.2A, R_G = 6Ω
Turn-On Rise Time	t_r	—	62	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	232	—	ns	
Turn-Off Fall Time	t_f	—	186	—	ns	

Notes:
5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
6. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

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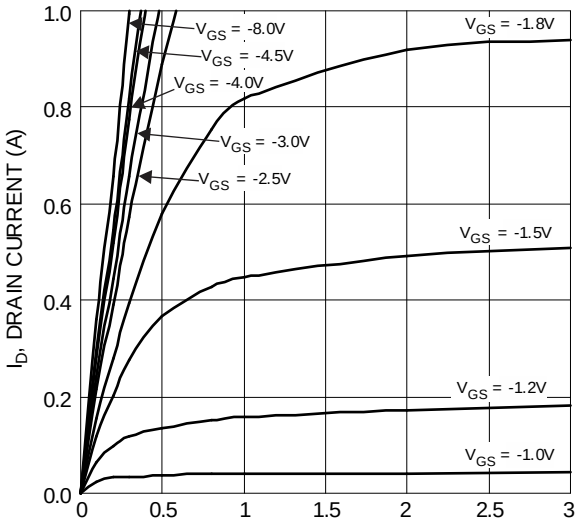

Figure 1 Typical Output Characteristics

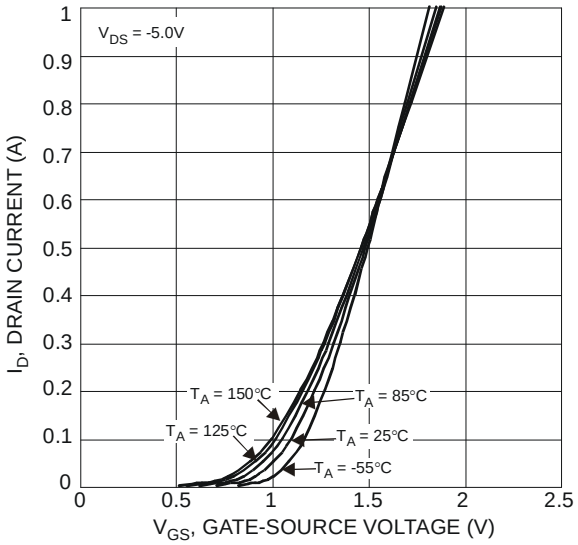

Figure 2 Typical Transfer Characteristics

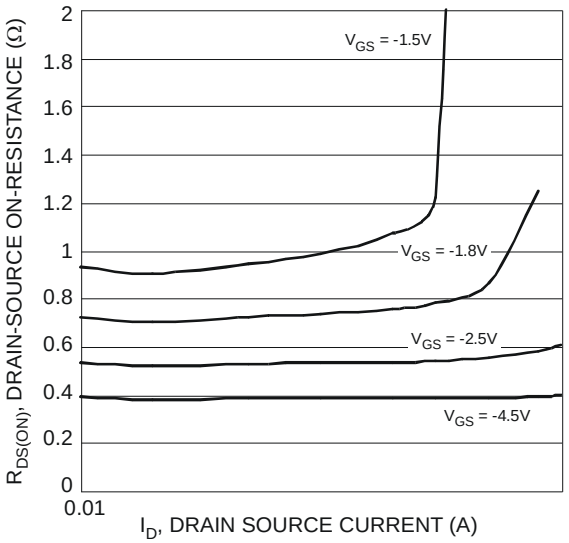

Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

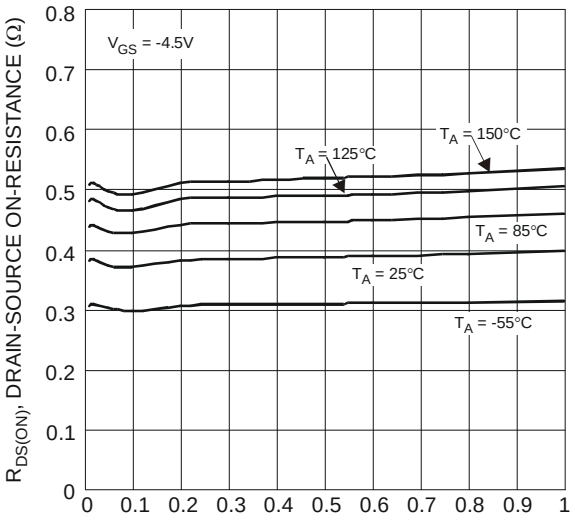

Figure 4 Typical On-Resistance vs. Drain Current and Temperature

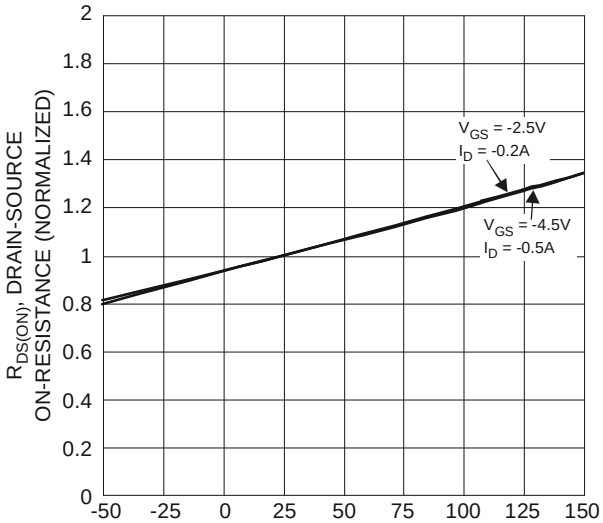

Figure 5 On-Resistance Variation with Temperature

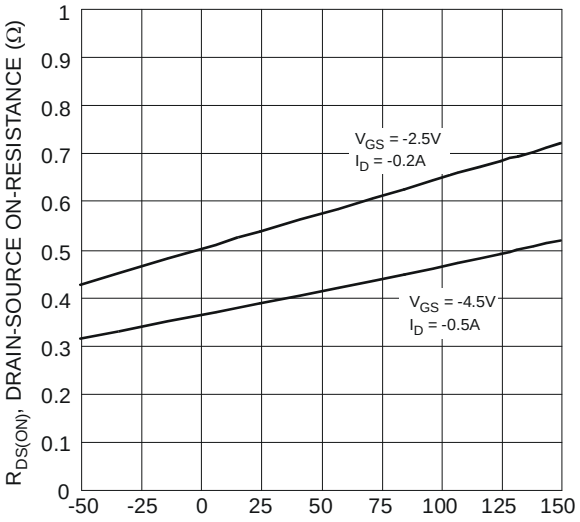

Figure 6 On-Resistance Variation with Temperature

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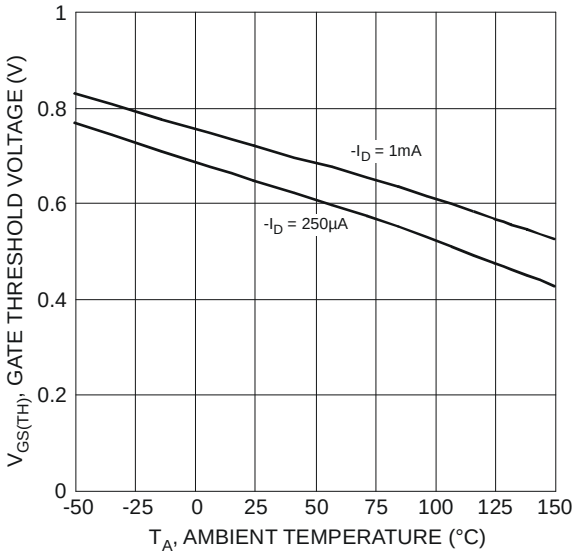

Figure 7 Gate Threshold Variation vs. Ambient Temperature

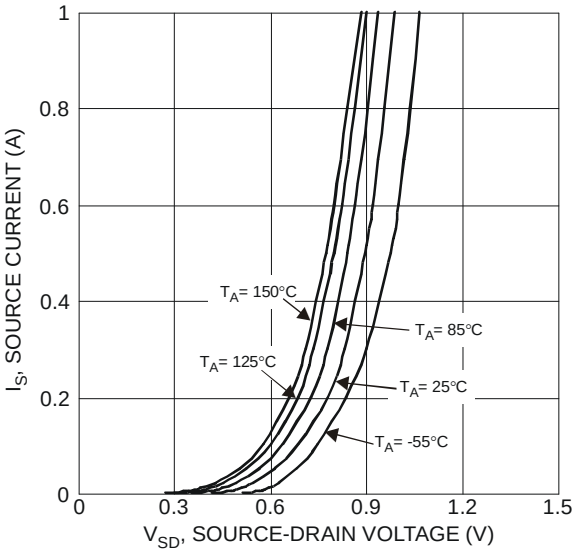

Figure 8 Diode Forward Voltage vs. Current

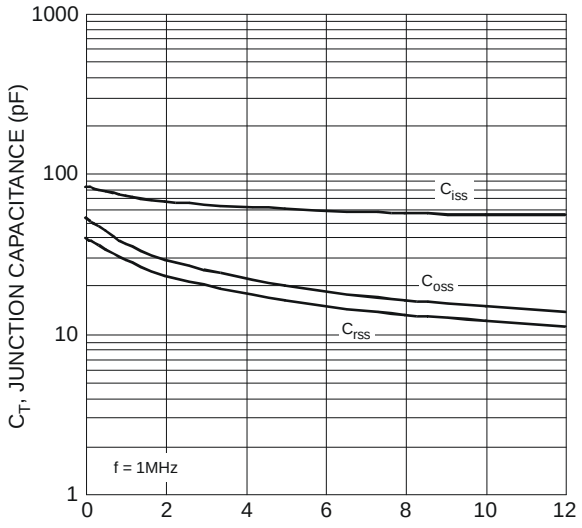

Figure 9 ypical Junction Capacitance

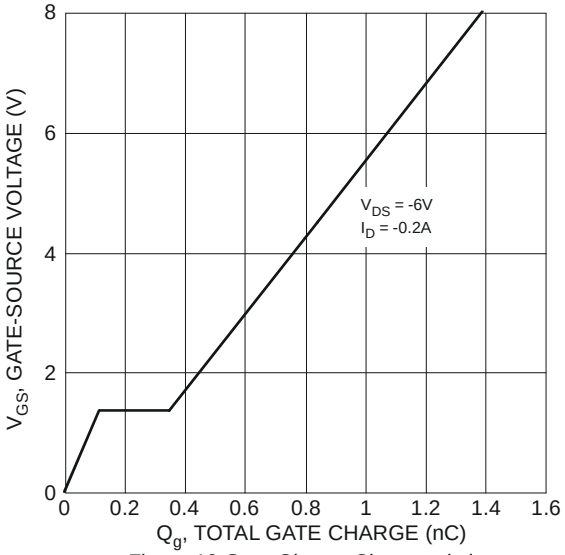

Figure 10 Gate-Charge Characteristics

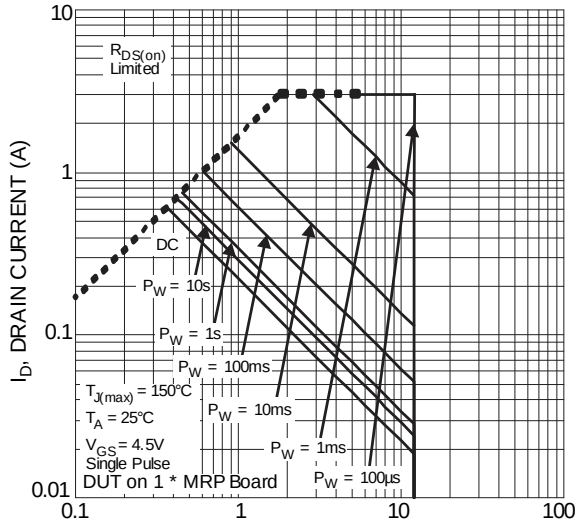

Figure 11 SOA, Safe Operation Area

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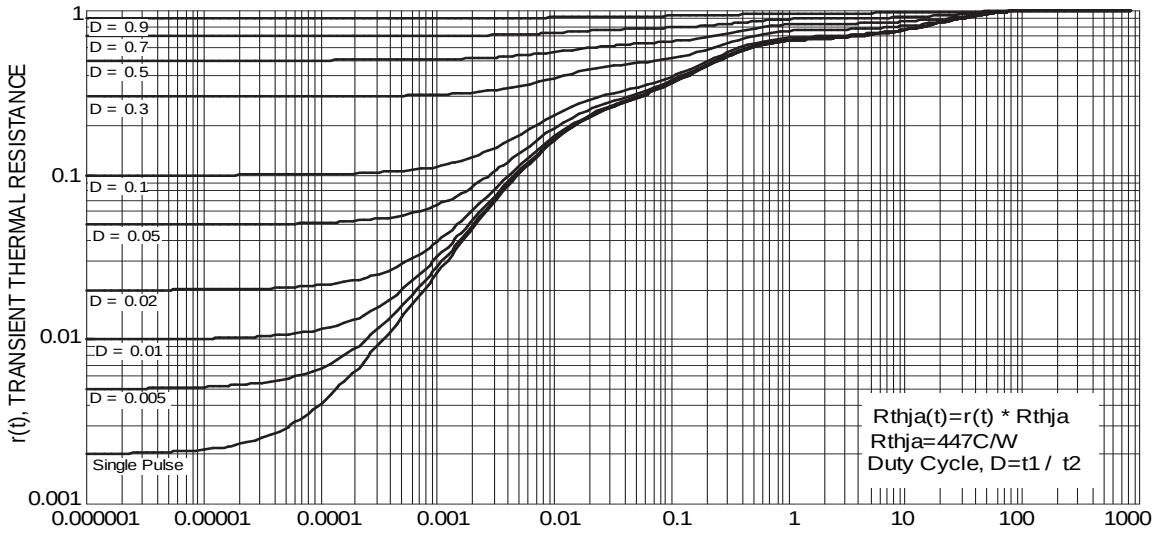
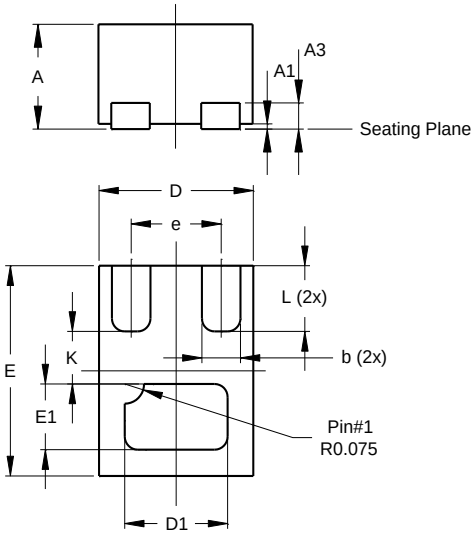


Figure 12 Transient Thermal Resistance

Package Outline Dimensions

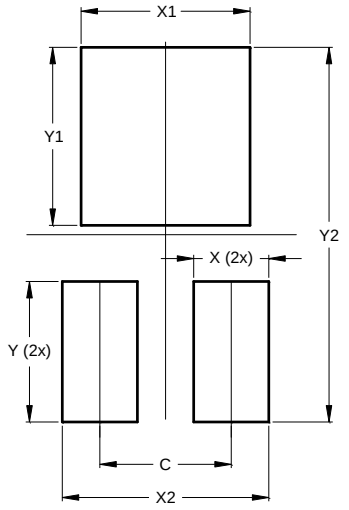
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN0806-3			
Dim	**Min**	**Max**	**Typ**
A	0.375	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.10
b	0.10	0.20	0.15
D	0.55	0.65	0.60
D1	0.35	0.45	0.40
E	0.75	0.85	0.80
E1	0.20	0.30	0.25
e	-	-	0.35
K	-	-	0.20
L	0.20	0.30	0.25
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	0.350
X	0.200
X1	0.450
X2	0.550
Y	0.375
Y1	0.475
Y2	1.000

NEW PRODUCT

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